









Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
08	156	FR4	35	L46.18_05.35	P10	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_156_FR4_35_L46.18_05.35_p10_s1

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		A1
	460 μ	L-FR4		
Layer-2	18 μ	Copper	 (100 μ PrePreg-Type: 2125)	A2
	100 μ	Prepreg		
Layer-3	35 μ	Copper		A3
	50 μ	L-FR4		
Layer-4	35 μ	Copper		A4
	100 μ	Prepreg		
Layer-5	35 μ	Copper		A3
	50 μ	L-FR4		
Layer-6	35 μ	Copper		A2
	100 μ	Prepreg		
Layer-7	18 μ	Copper		A1
	460 μ	L-FR4		
Layer-99	35 μ	Copper		

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